

Preliminary Datasheet. The technical statements are only guidelines and can be changed at any time.

6607Product Description

Modified epoxy | 1 part | solvent-free | thermal-curing | thermally conductive

Potting

Good metal bonding

Heat sink bonding

Curing Properties

This adhesive must be cured with heat. Typical curing temperatures are listed in the table below.

| Temperatures | Time |
|--------------|--------|
| 80°C | 60 min |
| 120°C | 30 min |
| 150°C | 10 min |

The heat cure times are only provided as a guideline. They are derived from curing a 2g adhesive sample without affixed substrates in a laboratory environment. Actual cure times can vary based on part size, configuration, adhesive volume and temperature control required for the component substrates to attain oven temperature.

The final bond strength of the adhesive is achieved no sooner than 24 h after the bonded components are removed from the oven.



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| Technical Data | |
|--|----------------------|
| | |
| Resin | Epoxy |
| Appearance | Gray |
| Filler | Aluminum oxide |
| Filler - weight [%] | 50 |
| Particle size D90 [µm] | 16 |
| Uncured Material | |
| Viscosity [mPas] (Kinexus Rheometer, 25 °C, 5s ⁻¹) | 50,000 – 65,000 |
| PE-Standard 064 | |
| Thixotropic index [1/10] PE-Standard 064 | 1.6 – 1.7 |
| Density [g/cm ³] | |
| PE-Standard 004 | 1.83 |
| Working life [h] | 40 |
| @ room temperature | 48 |
| Cured Material | |
| Hardness shore D | 78 – 88 |
| PE-Standard 006 | /8-88 |
| Temperature resistance [°C] | -40 - 200 |
| Linear shrinkage [%] | < 0,5 |
| PE-Standard 031 | |
| Water absorption [wt%] PE-Standard 016 | < 1 |
| | |
| Glass transition temperature - DSC [°C] | 90 – 115 |
| PE-Standard 009 Coefficient of thermal expansion [ppm/K] below Tg | |
| PE-Standard 017 | 32 – 37 |
| Coefficient of thermal expansion [ppm/K] above Tg | 120 150 |
| PE-Standard 017 | 120 – 150 |
| Thermal conductivity [W/m*K] | |
| PE-Standard 062 | 0.8 - 1.0 |
| Dielectric strength [kV/mm] | 18 |
| DIN EN 60243 | 18 |
| Volume resistivity [Ohm*cm] | 2 x 10 ¹⁵ |
| PE-Standard 040 | |
| Young´s modulus – Tensile test [MPa] | |
| 120°C, 30min | 5,100 – 6,500 |
| PE-Standard 056 | |
| Storage modulus – DMA [MPa] | |
| 130°C, 30min | 700 – 800 |
| PE-Standard 022 | |
| Tensile strength [MPa] | 10 20 |
| 120°C, 30min PE-Standard 014 | 18 – 30 |
| I L STAINAND OLT | |



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| Elongation at break [%] | |
|------------------------------------|-----------|
| 120°C, 30min | 0.4 – 0.5 |
| PE-Standard 014 | |
| Block Shear Test [MPa] (PCB) | |
| 150°C, 30min | 18 |
| PE-Standard 049 | |
| Block Shear Test [MPa] (PCB) | |
| 150°C, 30min/3 x Reflow 288°C, 10s | 16 |
| PE-Standard 049 | |

Transport/Storage/Shelf Life

| Package type | Transport | Storage | Shelf life* |
|-------------------|-----------|---------|--------------------------------|
| Syringe/Cartridge | -20°C | 20% | At delivery |
| Other packages | | -20°C | min. 3 months max. 6 months |

*Store in original, unopened containers!



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Instructions for use

Surface preparation

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP[®] from Panacol, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

Application

Our products are supplied ready to use. Depending on the packaging, our adhesives may be dispensed by hand directly from the package, or they can be applied using dispensing systems and automation. Many commercially available valve and controller options are available to ensure accurate and consistent adhesive dispensing. For assistance with dispensing and curing questions, please contact our Applications Engineering department. Adhesive and substrate should not be cold for proper bonding. They must be allowed to warm to room temperature prior to processing. After curing, the adhesive must be allowed to cool to ambient temperature before testing the product's performance. For safety information refer to our Material Safety Data Sheet (MSDS).

Storage

Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Panacol cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!



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Disclaimer

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

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Contact

Panacol-Elosol GmbH Stierstädter Straße 4 61449 Steinbach Germany Phone: +49 6171 6202-0 Mail: info@panacol.de www.panacol.com Panacol-USA, Inc. 142 Industrial Lane Torrington CT 06790 USA Phone: +1 860-738-7449 Mail: info@panacol-usa.com www.panacol-usa.com Panacol-Korea Co., Ltd. #707, Kranz Techno, 388 Dunchon-daero Junwon-gu, Seongnam Gyeonggi-do, 13403 KOREA Phone: +82 31 749 1701 Mail: info@panacol-korea.com Eleco Panacol – EFD 125, av Louis Roche Z.A. des Basses Noëls 92238 Gennevilliers Cdx FRANCE Tél.: +33 (0)1 47 92 41 80 Mail: eleco@eleco-panacol.fr www.eleco-panacol.fr

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